# DATA SHEET

# 2.45 GHz ISM-band antenna for Bluetooth and WLAN IEEE 802.11b (Long Shape)

Surface-mount ceramic multilayer antennas

**Product specification** 

2002 July 08 Rev.0



### Surface-mount ceramic multilayer antennas

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#### **FEATURES**

- · Designed for 2.45 GHz ISM-band
- · Simplifies antenna circuitry
- NiSn lead-free terminations
- suitable for wave and reflow soldering
- · Supplied in tape on reel.

#### **APPLICATIONS**

- Telecommunications
- Computing (PCs, printers, PDAs)
- Wireless office data communications including WLAN
- Consumer electronics (wireless headphones).

#### **DESCRIPTION**

This 2.45 GHz ceramic multilayer antenna has been designed to meet the requirements of the Bluetooth  $^{TM(1)}$  and IEEE 802.11b wireless communications protocol. It consists of a rectangular block of low-dielectric ceramic material and is fabricated in a water-based non-toxic process. The antenna is capable of providing good connectivity using near 50  $\Omega$  microstrip directly onto the PC board.

#### **ENVIRONMENTAL CARE**



The foil making process uses an environmentfriendly aqueous-solvent technology that fully

complies with today's green-product design requirements. All terminations are lead-free. Packing materials can be recycled.

### **QUICK REFERENCE DATA**

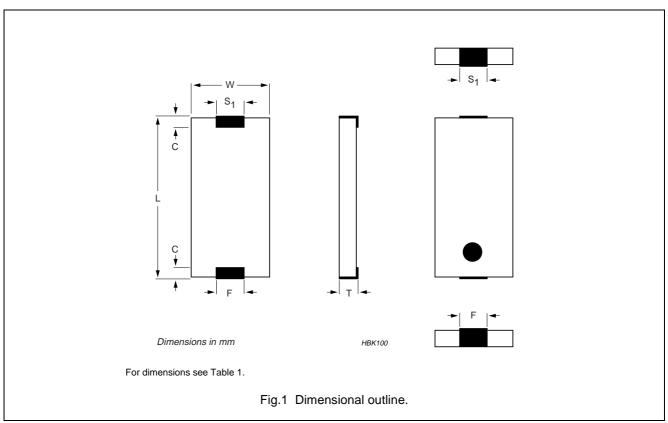
| DESCRIPTION                  | VALUE                   |
|------------------------------|-------------------------|
| Center frequency             | 2.45, 2.60 and 2.70 GHz |
| Bandwidth                    | 100 MHz                 |
| Gain                         | 0 dBi max.              |
| VSWR                         | 2 max.                  |
| Polarization                 | Linear                  |
| Azimuth beamwidth            | Omni-directional        |
| Impedance                    | 50 Ω                    |
| Power dissipation            | 1 W                     |
| Operating temperature        | −55 to +125 °C          |
| Terminations                 | NiSn                    |
| Resistance to soldering heat | 260 °C for 10 s         |
| Weight                       | 0.16 g                  |

Bluetooth is a trademark owned by Telefonieaktiebolaget L M Ericsson, Sweden.

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### **MECHANICAL DATA**



### **Physical dimensions**

Table 1 Antenna dimensions

| L                         | W        | Т        | F                   | С        | S <sub>1</sub>              |
|---------------------------|----------|----------|---------------------|----------|-----------------------------|
| -                         | -        | -        | feed<br>termination | -        | NC<br>solder<br>termination |
| Dimensions in millimetres |          |          |                     |          |                             |
| 8.0 ±0.25                 | 3.5 ±0.2 | 0.9 ±0.2 | 1.25 ±0.25          | 0.5 ±0.3 | 1.25 ±0.35                  |

### **Device marking**

| CENTER<br>FREQUENCY<br>(GHZ) | MARKING<br>CODE |  |
|------------------------------|-----------------|--|
| 2.45                         | no marking      |  |
| 2.60                         | 6               |  |
| 2.70                         | 7               |  |

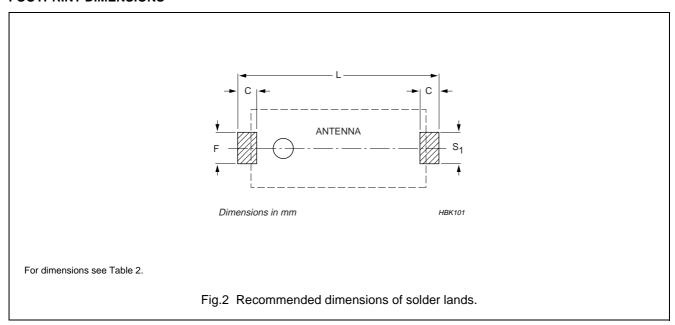
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#### **ELECTRICAL CHARACTERISTICS**

| DESCRIPTION                  | VALUE                   |
|------------------------------|-------------------------|
| Center frequency             | 2.45, 2.60 and 2.70 GHz |
| Bandwidth                    | 100 MHz                 |
| Gain                         | 0 dBi max.              |
| VSWR                         | 2 max.                  |
| Polarization                 | Linear                  |
| Azimuth beamwidth            | Omni-directional        |
| Impedance                    | 50 Ω                    |
| Power dissipation            | 1 W                     |
| Operating temperature        | -55 to +125 °C          |
| Terminations                 | NiSn                    |
| Resistance to soldering heat | 260 °C, 10 sec.         |

### **FOOTPRINT DIMENSIONS**



### **Physical dimensions**

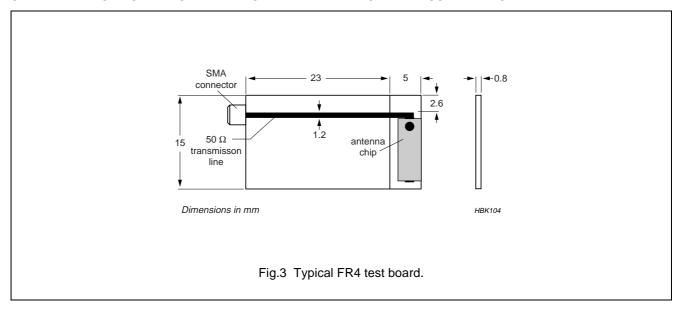
Table 2 Recommended solder land pattern

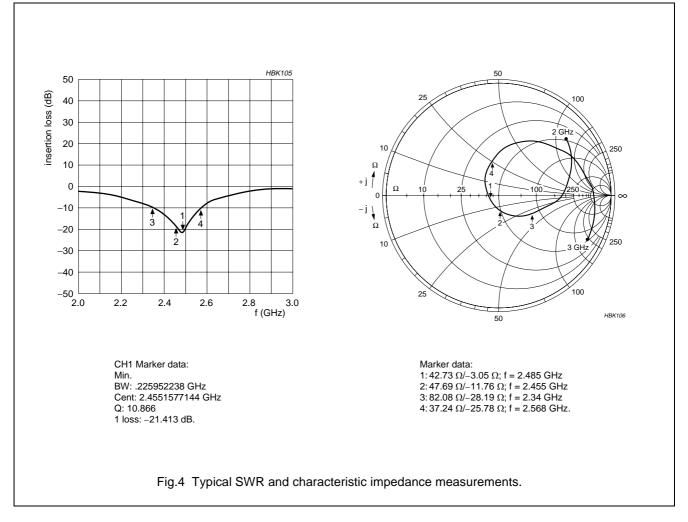
| L          | F                         | С          | S <sub>1</sub>     |  |
|------------|---------------------------|------------|--------------------|--|
| _          | feed pad                  | -          | NC<br>mounting pad |  |
| Dimensions | Dimensions in millimetres |            |                    |  |
| 9.0 ±0.10  | 1.40 ±0.10                | 0.90 ±0.10 | 1.40 ±0.10         |  |

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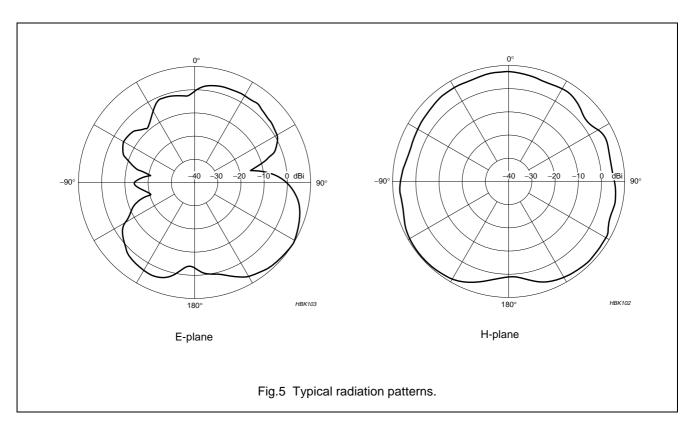
#### STANDARD TEST BOARD FOR RADIATION PATTERN AND SWR MEASUREMENTS



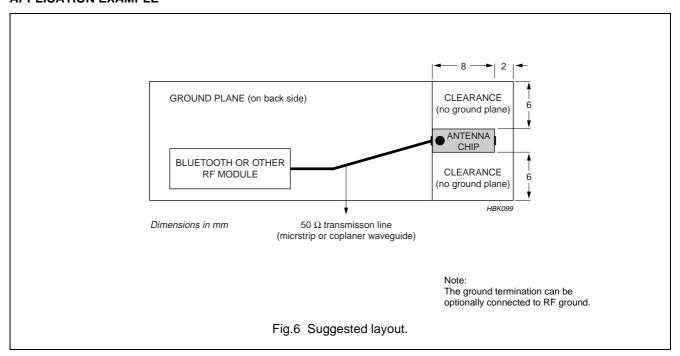


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### **APPLICATION EXAMPLE**



### Surface-mount ceramic multilayer antennas

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#### ORDERING INFORMATION

Components may be ordered by using either a simple 16-digit clear text code or Phycomp's unique 12NC.

Ordering example for a 2.45 GHz antenna, 1000 pieces supplied in blister tape on 180 mm reel.

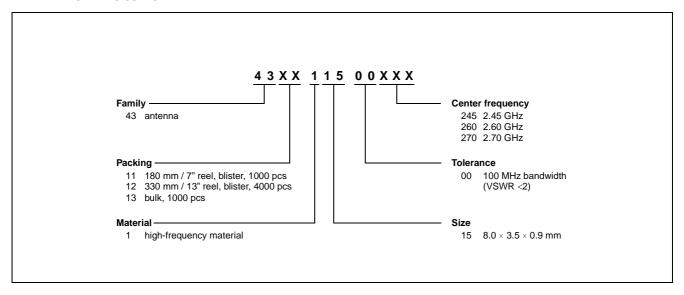
### Clear text ordering code

EXAMPLE: AN2450000708031K

| PRODUCT      | CENTER<br>FREQUENCY                                   | BANDWIDTH    | MATERIAL | SIZE                         | QUANTITY                     | PACKING                                                            |
|--------------|-------------------------------------------------------|--------------|----------|------------------------------|------------------------------|--------------------------------------------------------------------|
| AN           | 2450                                                  | 00           | 07       | 0803                         | 1                            | К                                                                  |
| AN = antenna | 2450 = 2.45 GHz<br>2600 = 2.60 GHz<br>2700 = 2.70 GHz | 00 = 100 MHz | 07 = K7  | 0803 =<br>8.0 × 3.5 × 0.9 mm | 1 = 1000 pcs<br>4 = 4000 pcs | K = 180 mm; 7" blister<br>F = 330 mm; 13" blister<br>B = bulk case |

### 12NC ordering code

EXAMPLE: 4311 115 00245



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### **TESTS AND REQUIREMENTS**

Table 3 Test procedures and requirements

| IEC<br>60 384-10<br>CECC<br>32 100<br>CLAUSE | IEC<br>60068-2<br>TEST<br>METHOD | TEST                                        | PROCEDURE                                                                                                                                                                           | REQUIREMENTS                                                                                  |
|----------------------------------------------|----------------------------------|---------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------|
| 4.4                                          |                                  | mounting                                    | The antenna may be mounted on a printed-circuit boards or ceramic substrates by applying wave soldering, reflow soldering (including vapour phase soldering) or conductive adhesive | no visual damage                                                                              |
| 4.5                                          |                                  | visual inspection<br>and dimension<br>check | any applicable method using ×10 magnification                                                                                                                                       | no cracks or fissures larger than 4 mm                                                        |
| 4.6.1                                        |                                  | antenna                                     | frequency: 2.45 GHz @ 20 °C                                                                                                                                                         | standard test board from Fig.3                                                                |
| 4.8                                          |                                  | adhesion                                    | a force of 5 N applied for 10 s to the line joining the terminations and in a plane parallel to the substrate                                                                       | no visible damage                                                                             |
| 4.9                                          |                                  | bond strength of plating on end             | mounted in accordance with CECC 32 100, paragraph 4.4                                                                                                                               | no visible damage                                                                             |
|                                              |                                  | face                                        | conditions: bending 1 mm at a rate of<br>1 mm/s; radius jig: 340 mm; 2 mm<br>warp on FR4 board of 90 mm length                                                                      | no visible damage                                                                             |
| 4.10                                         | 20 (Tb)                          | resistance to soldering heat                | 260 ±5 °C for 10 ±0.5 s in a static solder bath                                                                                                                                     | the terminations shall be well<br>tinned after recovery; center<br>frequency shift within ±6% |
|                                              |                                  | resistance to leaching                      | 260 ±5 °C for 30 ±1 s in a static solder bath                                                                                                                                       | using visual enlargement of ×10; dissolution of the terminations shall not exceed 10%         |
| 4.11                                         | 20 (Ta)                          | solderability                               | zero hour test and test after storage (20 to 24 months) in original packing in normal atmosphere; unmounted chips completely immersed for 2 ±0.5 s in a solder bath at 235 ±5 °C    | the terminations must be well tinned for at least 75%                                         |
| 4.12                                         | 4 (Na)                           | rapid change of temperature                 | -55 °C (30 minutes) to +125 °C (30 minutes); 100 cycles                                                                                                                             | no visual damage; center frequency shift within ±6%                                           |
| 4.14                                         | 3 (Ca)                           | damp heat                                   | 500 ±12 hours at 60 °C; 90 to 95% RH                                                                                                                                                | no visual damage; 2 hours recovery; center frequency shift within ±6%                         |
| 4.15                                         |                                  | endurance                                   | 500 ±12 hours at 125 °C                                                                                                                                                             | no visual damage; 2 hours recovery; center frequency shift within ±6%                         |

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### **REVISION HISTORY**

| Revision | Date        | Change<br>Notification | Description                         |
|----------|-------------|------------------------|-------------------------------------|
| Rev.0    | 2002 Jul 08 | _                      | - First issue of this specification |
|          |             |                        |                                     |